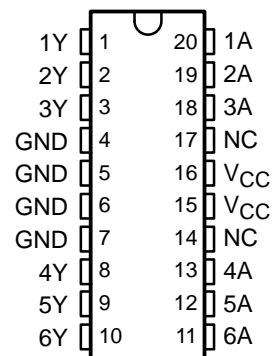


- Flow-Through Architecture Optimizes PCB Layout
- Center-Pin V_{CC} and GND Configuration Minimizes High-Speed Switching Noise
- **EPIC™** (Enhanced-Performance Implanted CMOS) 1- μ m Process
- 500-mA Typical Latch-Up Immunity at 125°C
- Package Options Include Plastic Small-Outline (DW) and Shrink Small-Outline (DB) Packages, and Standard Plastic 300-mil DIPs (N)

DB, DW, OR N PACKAGE
(TOP VIEW)



NC – No internal connection

description

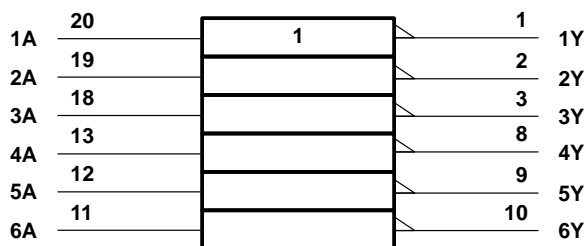
This device contains six independent inverters. It performs the Boolean function $Y = \bar{A}$.

The 74AC11004 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE
(each inverter)

INPUT A	OUTPUT Y
H	L
L	H

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



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**TEXAS
INSTRUMENTS**

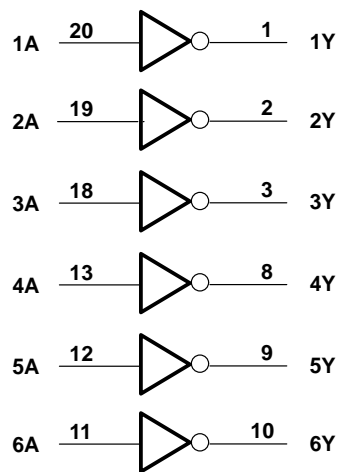
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74AC11004
HEX INVERTER

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logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to $V_{CC} + 0.5$ V
Output voltage range, V_O (see Note 1)	–0.5 V to $V_{CC} + 0.5$ V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	±50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±50 mA
Continuous current through V_{CC} or GND	±100 mA
Maximum power dissipation at $T_A = 55^{\circ}\text{C}$ (in still air) (see Note 2):	
DW package	1.6 W
DB package	0.6 W
N package	1.3 W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the N package, which has a trace length of zero.

recommended operating conditions

			MIN	NOM	MAX	UNIT
V _{CC}	Supply voltage		3	5	5.5	V
V _{IH}	High-level input voltage	V _{CC} = 3 V	2.1			V
		V _{CC} = 4.5 V	3.15			
		V _{CC} = 5.5 V	3.85			
V _{IL}	Low-level input voltage	V _{CC} = 3 V			0.9	V
		V _{CC} = 4.5 V			1.35	
		V _{CC} = 5.5 V			1.65	
V _I	Input voltage		0		V _{CC}	V
V _O	Output voltage		0		V _{CC}	V
I _{OH}	High-level output current	V _{CC} = 3 V			–4	mA
		V _{CC} = 4.5 V			–24	
		V _{CC} = 5.5 V			–24	
I _{OL}	Low-level output current	V _{CC} = 3 V			12	mA
		V _{CC} = 4.5 V			24	
		V _{CC} = 5.5 V			24	
Δt/Δv	Input transition rise or fall rate		0		10	ns/V
T _A	Operating free-air temperature		–40		85	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
V _{OH}	I _{OH} = –50 μA	3 V	2.9			2.9		V
		4.5 V	4.4			4.4		
		5.5 V	5.4			5.4		
	I _{OH} = –4 mA	3 V	2.58			2.48		
		4.5 V	3.94			3.8		
		5.5 V	4.94			4.8		
	I _{OH} = –75 mA [†]	5.5 V				3.85		
V _{OL}	I _{OL} = 50 μA	3 V			0.1		0.1	V
		4.5 V			0.1		0.1	
		5.5 V			0.1		0.1	
	I _{OL} = 12 mA	3 V			0.36		0.44	
		4.5 V			0.36		0.44	
		5.5 V			0.36		0.44	
	I _{OL} = 75 mA [†]	5.5 V					1.65	
I _I	V _I = V _{CC} or GND	5.5 V			±0.1		±1	μA
I _{CC}	V _I = V _{CC} or GND, I _O = 0	5.5 V			4		40	μA
C _i	V _I = V _{CC} or GND	5 V		3.5				pF

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

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switching characteristics over recommended operating free-air temperature range,
 $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$T_A = 25^\circ\text{C}$			MIN	MAX	UNIT
			MIN	TYP	MAX			
t_{PLH}	A	Y	1.5	6.1	9	1.5	10	ns
t_{PHL}			1.5	5.2	7.4	1.5	8.2	

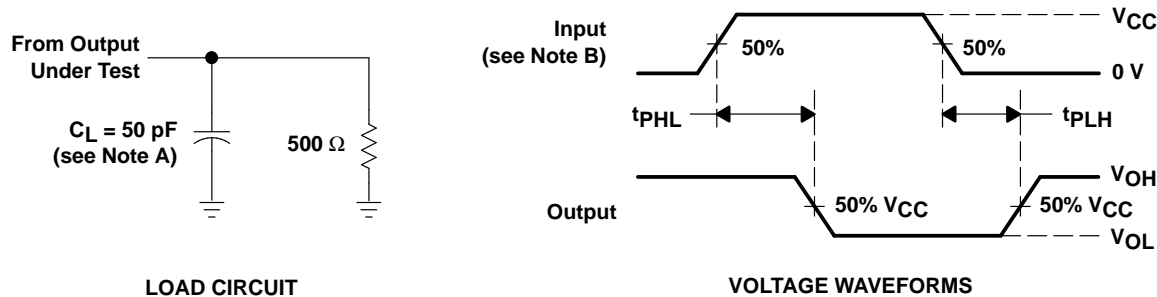
switching characteristics over recommended operating free-air temperature range,
 $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$T_A = 25^\circ\text{C}$			MIN	MAX	UNIT
			MIN	TYP	MAX			
t_{PLH}	A	Y	1.5	4.2	6.3	1.5	7.1	ns
t_{PHL}			1.5	3.8	5.5	1.5	6	

operating characteristics, $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per inverter	$C_L = 50\text{ pF}$, $f = 1\text{ MHz}$	29	pF

PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C_L includes probe and jig capacitance.
B. Input pulses are supplied by generators having the following characteristics: $PRR \leq 1\text{ MHz}$, $Z_O = 50\text{ }\Omega$, $t_r = 3\text{ ns}$, $t_f = 3\text{ ns}$.
C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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